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YESTech Announces X-Series 3-D X-Ray Inspection System

New system brings cost-effective, advanced 3-D X-Ray inspection solutions to the market

San Clemente, CA – June 12, 2008 – YESTech, a leading supplier of automated optical and x-ray inspection systems for the electronics industry, announced its new X3, 3-D X-Ray inspection system for populated printed circuit boards. The innovative new X-Series Automated X-Ray Inspection System (AXI) offers printed circuit board assembly manufacturers advanced 3-D inspection capability for fast and complete inspection of PCBs with BGAs and other hidden solder joints.

The X3's proprietary imaging technology rapidly gathers multiple oblique images of the sample to construct a 3 dimensional rendering used in identifying solder and component related defects on both single and double-sided boards. The X3's unique ability to selectively use 2-D or 3-D technology to inspect specific regions of interest on a board, provides a critical advantage of balancing double sided inspection and throughput.

The X3 allows users to discriminate between the top and bottom sides of boards where there is a high-density of solder joints. YESTech's 3-D capability separates the top and bottom images of double sided boards for unimpeded automated inspection of solder joints. When integrated with YESTech AOI inspection, these systems can increase fault coverage to include nearly all process defects.

Programming the X-Series is fast and intuitive, with a typical inspection program being created by operators in less than 45 minutes. Utilization of standard package libraries simplifies training and insures program portability across manufacturing lines. The X-Series is equally well suited for in-line or off-line applications and offers precise solder joint inspection, fast throughput and ultra low false calls. In addition, YESTech's remote programming maximizes system utilization and the real-time SPC software, included with the system, provides a valuable yield enhancement solution.

Don Miller, YESTech President, states, "The X3 offers the new option for 3-D X-Ray inspection." He adds, "The X3 is another milestone for YESTech, bringing this important 3-D X-Ray technology to the industry, with the fastest return on investment available."

Editor's Note: A high-resolution image of the YTX X-Series 3-D X-Ray is available by calling (949) 439-5351 or by visiting http://www.kreativesolution.com/yestech_x_series.htm For additional product and pricing information, visit our website or email us at: sales@yestechinc.com

About YESTech

Headquartered in San Clemente, California, YESTech is a leading provider of automated optical and high-resolution x-ray inspection systems, with integrated yield enhancement solutions for the printed circuit board assembly and advanced semiconductor-packaging industries. Founded in 2002 and acquired in 2007 as a subsidiary of Nordson Corporation (Nasdaq:NDSN), YESTech is operated and managed by a team of industry experts with a history of success, bringing powerful and cost-effective inspection to the electronics market. The company has sales offices and customer support centers in North America, Asia and Europe. For more information on YESTech and its products, visit www.yestechinc.com For more information on Nordson Corporation visit <http://www.nordson.com>